



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|---|
| Chip Size | 0805 |
| L | 2.01mm +0.81/-0.25mm (0.079 in +0.032/-0.01 in) |
| W | 1.27mm +0.68/-0.25mm (0.05 in +0.027/-0.01 in) |
| T | 1.57mm MAX (0.062 in MAX) |
| B | 0.51mm +/-0.25mm (0.02 in +/-0.01 in) |

Packaging Specifications

| | |
|--------------------|--------|
| Packaging | Waffle |
| Packaging Quantity | 80 |

General Information

| | |
|------------------|--|
| Series | SMD MIL X7R PRF32535 |
| Style | SMD Chip |
| Description | SMD, Military, Low ESR, MIL-PRF-32535 |
| RoHS | No |
| Prop 65 | ⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov . |
| Termination | Solder Dipped |
| Failure Rate | N/A |
| Qualifications | MIL-PRF-32535 |
| AEC-Q200 | No |
| Component Weight | 20 mg |

Specifications

| | |
|---------------------------------|---------------------|
| Capacitance | 0.47 uF |
| Capacitance Tolerance | 5% |
| Voltage DC | 25 VDC |
| Dielectric Withstanding Voltage | 62.5 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | X7R |
| Dissipation Factor | 3.5% 1 MHz 25C |
| Aging Rate | 3% Loss/Decade Hour |
| Insulation Resistance | 2.13 GOhms |

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)